

Tool ID: 821  
Tool Location: 133

Equipment Information Sheet

# Suss SB8e Substrate Bonder

**Manager:** Christopher Alpha 607-254-4913

**Backup:** Roberto Panepucci 607-254-4855

**Backup:** Giovanni Sartorello 607-254-4853

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

**SAFETY**

- Do not open the chamber manually until the temperature is below 100°C and the gas pressure is above 990 mBar
- Substrates and thermal chuck could be hot after processing

**USAGE RESTRICTIONS**

- No Buddy Restrictions

**SCHEDULING/SIGN-UP RESTRICTIONS**

Minimum Tool Time: 30 minutes

- None

**MATERIALS COMPATIBILITY CATEGORY**

Tool Category 5: Class A and B Metals and Compounds	
Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

**Additional Material Restrictions and Exceptions**

- Only metals evaporated at the CNF are allowed in the tool.
- Metal and other compression material can only be in the bonding interface
- For running pieces check with tool manager before running the tool.

Last Updated: 11/26/2024